

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4272455

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	SAMSUNG ELECTRO-MECHANICS CO., LTD.	02/10/2017
RECEIVING PARTY DATA		
Name:	SEMCNS CO., LTD.	
Street Address:	1F, 35, PANGYO-RO	
Internal Address:	255BEON-GIL, BUNDANG-GU	
City:	SEONGNAM-SI, GYEONGGI-DO	
State/Country:	KOREA, REPUBLIC OF	
Postal Code:	13486	
PROPERTY NUMBERS Total: 12		
Property Type	Number	
Application Number:	14981650	
Application Number:	14934803	
Application Number:	14887108	
Application Number:	14029684	
Application Number:	13548575	
Application Number:	12987697	
Application Number:	13017950	
Application Number:	12314206	
Application Number:	14260950	
Application Number:	12550812	
Application Number:	12510162	
Application Number:	12467542	
CORRESPONDENCE DATA		
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PATENT

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ATTORNEY DOCKET NUMBER:	102052-0011
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NAME OF SUBMITTER:	HOSANG LEE
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SIGNATURE:	/HOSANG LEE/
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DATE SIGNED:	02/13/2017
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Total Attachments: 3

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ASSIGNMENT

WHEREAS, SAMSUNG ELECTRO-MECHANICS CO., LTD. , a corporation organized under and pursuant to the laws of Korea having its principal place of business at Maeyoung-ro 150 (Maetan-dong), Youngtong-gu, Suwon-si, Gyeonggi-do, REPUBLIC OF KOREA (hereinafter referred to as Assignor), is the exclusive owner, by assignment, of the Patents and Applications listed in the attached Schedule A; and

WHEREAS, SEMCNS CO., LTD. , a corporation organized under and pursuant to the laws of Korea having its principal place of business at 1F, 35, Pangyo-ro 255beon-gil, Bundang-gu, Seongnam-si, Gyeonggi-do, REPUBLIC OF KOREA, 13486(hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in, to and under said Patent and the invention covered thereby;

NOW, THEREFORE, in consideration of and in exchange for the sum of One Dollar (\$1.00) and other good and valuable consideration, receipt of which is hereby acknowledged, the said Assignor has sold, assigned, transferred and set over, and does hereby sell, assign, transfer and set over to the said Assignee, the entire right, title and interest for the United States of America and all other countries in and to said applications for all original, divisional, continuation, continuation-in-part, substitute or reissue applications and patents applied for or granted therefore in the United States of America and all other countries on the attached list of *Schedule A*, and the Commissioner of Patents and Trademarks is hereby authorized and requested to issue all patents on *Schedule A* to said assignee herein, as assignee of the entire interest therein; and the undersigned for itself and its legal representatives, heirs and assigns does hereby agree and covenant without further remuneration, to execute and deliver all divisional, continuation, continuation-in-part, reissue and other applications for Letters Patent and all assignments thereof to said assignee or its assigns, to communicate to said assignee or its representatives all facts known to the undersigned respecting said invention listed on *Schedule A* whenever requested, to testify in any interferences or other legal proceedings in which said application or patent may become involved, to sign all lawful papers, make all rightful oaths, and do generally everything necessary to aid assignee, its successors, assigns and nominees to obtain patent protection for said invention listed on *Schedule A* in the United States of America and all other countries, the expenses incident to said application listed on *Schedule A* to be borne and paid by said assignee.

SCHEDULE A

Application/ Patent Number	Filing Date/Grant Date	Inventor	Title	Ctry
14/981,650	December 28, 2015	Jin Kyung JOO et al.	METHOD OF MANUFACTURING MULTILAYER CERAMIC ELECTRONIC COMPONENT	US
14/934,803	November 6, 2015	Yong Seok CHOI et al.	PROBE CARD	US
14/887,108	October 19, 2015	Taek Jung LEE et al.	MULTILAYER CERAMIC SUBSTRATE AND MANUFACTURING THEREOF	US
14/029,684	September 17, 2013	Yoon Hyuck CHOI et al.	PRE SPACE TRANSFORMER, SPACE TRANSFORMER MANUFACTURED USING THE PRE SPACE TRANSFORMER, AND SEMICONDUCTOR DEVICE INSPECTING APPARATUS INCLUDING THE SPACE TRANSFORMER	US
13/548,575	July 13, 2012	Won Hee YOO et al.	THIN FILM ELECTRODE CERAMIC SUBSTRATE AND METHOD FOR MANUFACTURING THE SAME	US
12/987,697	January 10, 2011	Myung Whun CHANG et al.	METHOD OF REPAIRING A PROBE BOARD	US
13/017,950	January 31, 2011	Je Hong SUNG et al.	METHOD FOR FABRICATING CERAMIC SUBSTRATE	US
12/314,206	December 5, 2008	Beom Joon CHO et al.	LAMINATED CERAMIC PACKAGE	US

14/260,950	April 24, 2014	Ji Sung NA et al.	LOW TEMPERATURE CO- FIRED CERAMIC SUBSTRATE WITH EMBEDDED CAPACITORS	US
12/550,812	August 31, 2009	Yoon Hyuck CHOI et al.	CIRCUIT BOARD MODULE AND METHOD OF MANUFACTURING THE SAME	US
12/510,162	July 27, 2009	Soo Hyun LYOO et al.	CERAMIC LAMINATE AND METHOD OF MANUFACTURING CERAMIC SINTERED BODY	US
12/467,542	May 18, 2009	Yun Hwi PARK et al.	MULTILAYER CERAMIC SUBSTRATE	US

Date: Feb. 10, 2017 Signature: M. G. Kim

Name: Moon Gune, Kim
Title: President
SEMCNS CO., LTD.